

ABSTRACT**PROCESS FOR CLEAVING A SUBSTRATE**

The present invention relates to a process for cleaving a substrate (1) for the purpose of detaching a film (1') therefrom, comprising the following successive steps:

- (i) the formation of what is called a stress-generating structure (2), locally bonded to the surface of the substrate (1) and designed to expand or contract in a plane parallel to the surface of the substrate (1) under the effect of a heat treatment; and
- (ii) the application of a heat treatment to said structure, designed to cause said structure (2) to expand or contract so as to generate a plurality of local stresses in the substrate (1), the combination of which generates a stress greater than the mechanical strength of the substrate in a cleavage plane (C) parallel to the surface of the substrate defining the film (1') to be detached, said stress leading to the cleavage of the substrate (1) over said plane (C).

Fig. 2